

Full Material Declaration for attached parts list

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Declarations authorised by

Udo Steinebrunner, Product Manager, -

Declaration effective from: 22 September 2010 [Approved: 07 July 2023 13:51 GMT]

Individual materials in the part			Individual substances in each material		
Use/Location	Material Group	Max mass %	Substance	CAS Number	Max mass %
Chip (die)	Other inorganic materials	0.06%	Gold	7440-57-5	11.5%
			Silica, amorphous-fused	60676-86-0	26%
			Silicon	7440-21-3	62.5%
			Silver	7440-22-4	2.5%
			Tin	7440-31-5	5%
Die attach	Sn-Pb solder	0.03%	Lead EU RoHS Exemption 7(a) Exempt from other regulatory requirements Exempt from other regulatory requirements	7439-92-1	92.5%
Encapsulation	EP (Epoxy resin)	41.58%	Carbon black	1333-86-4	0.3%
			ERL-2795	25068-38-6	28.3%
			Quartz sand	60676-86-0	71.4%
Leadfinish	Tin plating	0.48%	Tin	7440-31-5	100%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	57.85%	Copper	7440-50-8	100%

Attached parts list

Part number	Part name
TO-263-7L	Diode/Transistor Power